RB521S30T1

Schottky Barrier Diode

These Schottky barrier diodes are designed for high-speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand-held and portable applications where space is limited.

Features

- Extremely Fast Switching Speed
- Extremely Low Forward Voltage 0.5 V (max) @ $I_F = 200 \text{ mA}$
- Low Reverse Current
- Pb-Free Package is Available

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	V_R	30	Vdc
Forward Current DC	ΙF	200	mA
Peak Forward Surge Current (Note 1)	I _{FSM}	1.0	Α
ESD Rating: Class 1C per Human Body Model Class C per Machine Model			

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. 60 Hz for 1 cycle.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 2) T _A = 25°C	P _D	200	mW
Derate above 25°C		1.57	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +125	°C

2. FR-5 Minimum Pad.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Leakage (V _R = 10 V)	I _R	-	-	30.0	μΑ
Forward Voltage (I _F = 200 mA)	V _F	-	-	0.50	Vdc



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30 V SCHOTTKY BARRIER DIODE





SOD-523 CASE 502 PLASTIC

MARKING DIAGRAM



5M = Device Code M = Date Code* ■ Pb-Free Package

(Note: Microdot may be in either location)*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
RB521S30T1	SOD-523	4 mm Pitch 3000/Tape & Reel
RB521S30T1G	SOD-523 (Pb-Free)	4 mm Pitch 3000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

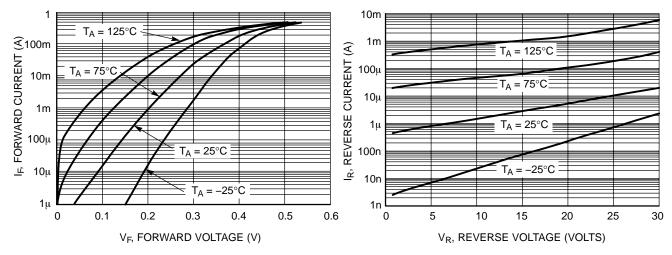


Figure 1. Forward Characteristics

Figure 2. Reverse Characteristics

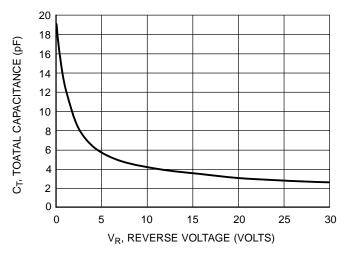
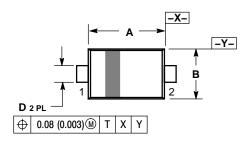


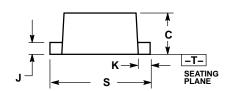
Figure 3. Total Capacitance

RB521S30T1

PACKAGE DIMENSIONS

SOD-523 CASE 502-01 ISSUE B



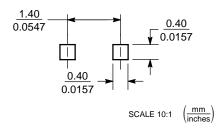


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982
- 2. CONTROLLING DIMENSION: MILLIMETER.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS INCHES					
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.10	1.20	1.30	0.043	0.047	0.051
В	0.70	0.80	0.90	0.028	0.032	0.035
n	0.50	0.60	0.70	0.020	0.024	0.028
D	0.25	0.30	0.35	0.010	0.012	0.014
ſ	0.07	0.14	0.20	0.0028	0.0055	0.0079
K	0.15	0.20	0.25	0.006	0.008	0.010
S	1.50	1.60	1.70	0.059	0.063	0.067

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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